

**1x512K x32bit DRAM Card**  
**2x512K x32bit DRAM Card**

**MF12M1-L57ATXX**  
**MF14M1-L57ATXX**

Connector Type

**Two-piece 88-pin**

**DESCRIPTION**

These DRAM CARDS are developed based on JEIDA DRAM CARD GUIDELINE Ver 2.0. These cards are made using industry standard 512K × 8 Dynamic RAM and interface IC's in TSOP.

- Extend refresh mode is available. (128 ms/1024 cycle)

**FEATURES**

- Operating Voltage :  $V_{CC} = 5V \pm 5\%$
- All inputs except  $\overline{RAS}$  inputs are buffered.
- Standard card size : 54 mm (W) × 85.6 mm (L) × 3.3mm (T)
- 88pin 2 piece connector type.
- $\overline{RAS}$  only refresh mode,  $\overline{CAS}$  before  $\overline{RAS}$  refresh mode and Page mode functions are available.

**APPLICATIONS**

Main/expansion memory unit for Personal Computer, Laser-Printer, FAX etc.

**PRODUCT LIST**

Product No	Item Type name	Memory capacity	Data bus width (bits)	Access time (t <sub>RAC</sub> ) (ns)	Connector type	Number of pins	Outline drawing
No. 1	MF12M1-L57ATXX	2 MB	32	70	Two-Piece	88	88P-001
No. 2	MF14M1-L57ATXX	4 MB		70			

DYNAMIC RAM CARDS

PIN ASSIGNMENT (No.1)

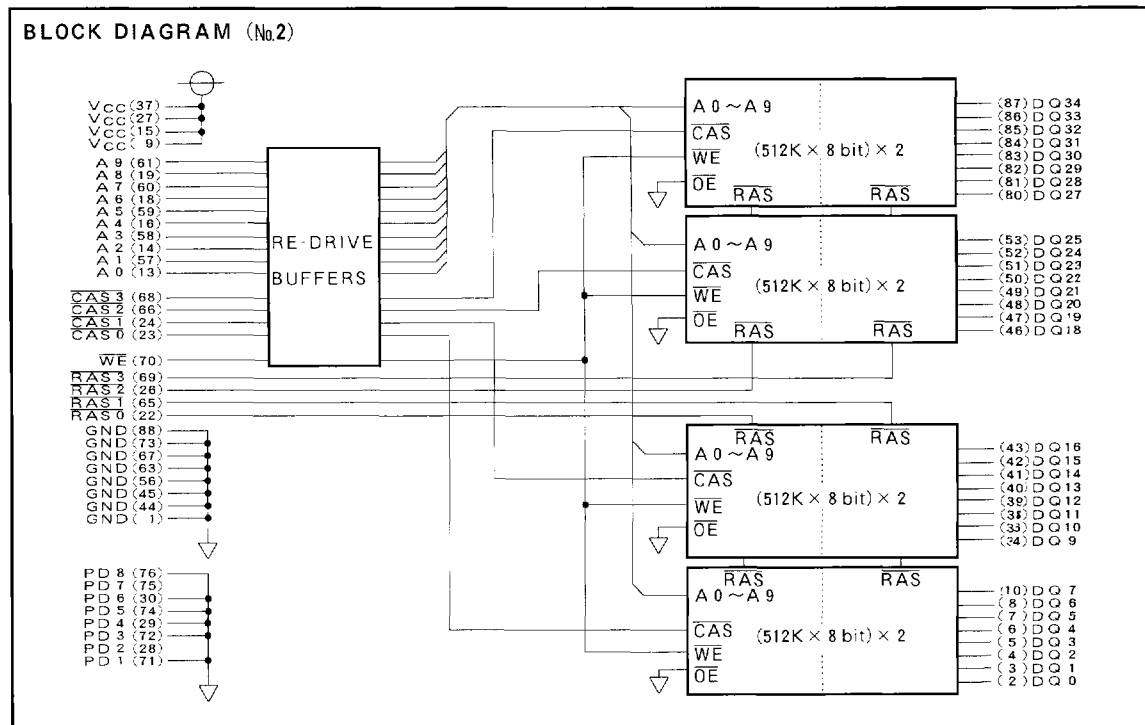
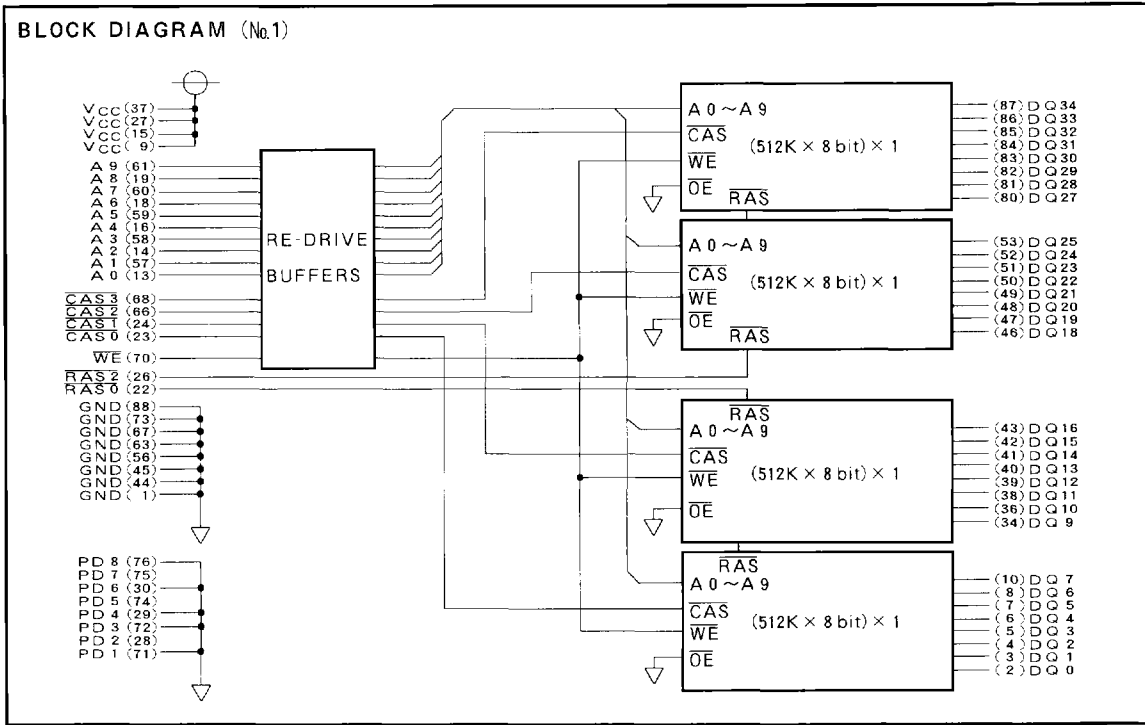
Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	45	GND	Ground
2	DQ 0	Data I/O	46	DQ18	Data I/O
3	DQ 1		47	DQ19	
4	DQ 2		48	DQ20	
5	DQ 3		49	DQ21	
6	DQ 4		50	DQ22	
7	DQ 5		51	DQ23	
8	DQ 6		52	DQ24	
9	N.C.	Power supply voltage	53	DQ25	Data I/O
10	DQ 7	Data I/O	54	N.C.	
11	N.C.	No connection	55	N.C.	
12	N.C.		56	GND	Ground
13	A 0	Address input	57	A 1	Address input
14	A 2		58	A 3	
15	V <sub>CC</sub>	Power supply voltage	59	A 5	Address input
16	A 4	Address input	60	A 7	
17	N.C.	No connection	61	A 9	
18	A 6	Address input	62	N.C.	No connection
19	A 8		63	GND	Ground
20	N.C.	No connection	64	N.C.	No connection
21	N.C.		65	N.C.	
22	RAS 0	Row address strobe 0	66	CAS 2	Column address strobe 2
23	CAS 0	Column address strobe 0	67	GND	Ground
24	CAS 1	Column address strobe 1	68	CAS 3	Column address strobe 3
25	N.C.	No connection	69	N.C.	No connection
26	RAS 2	Row address strobe 2	70	WE	Write enable
27	V <sub>CC</sub>	Power supply voltage	71	PD 1 (N.C.)	Presence detect 1
28	PD 2 (GND)	Presence detect 2	72	PD 3 (GND)	Presence detect 3
29	PD 4 (GND)	Presence detect 4	73	GND	Ground
30	PD 6 (GND)	Presence detect 6	74	PD 5 (N.C.)	Presence detect 5
31	N.C.	No connection	75	PD 7 (N.C.)	Presence detect 7
32	N.C.		76	PD 8 (N.C.)	Presence detect 8
33	N.C.		77	N.C.	No connection
34	DQ 9	Data I/O	78	N.C.	
35	N.C.	No connection	79	N.C.	
36	DQ10	Data I/O	80	DQ27	Data I/O
37	V <sub>CC</sub>	Power supply voltage	81	DQ28	
38	DQ11	Data I/O	82	DQ29	
39	DQ12		83	DQ30	
40	DQ13		84	DQ31	
41	DQ14		85	DQ32	
42	DQ15		86	DQ33	
43	DQ16		87	DQ34	
44	GND		Ground	88	GND

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PIN ASSIGNMENT (No.2)

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	GND	Ground	45	GND	Ground
2	DQ 0	Data I/O	46	DQ18	Data I/O
3	DQ 1		47	DQ19	
4	DQ 2		48	DQ20	
5	DQ 3		49	DQ21	
6	DQ 4		50	DQ22	
7	DQ 5		51	DQ23	
8	DQ 6		52	DQ24	
9	V <sub>cc</sub>		Power supply voltage	53	
10	DQ 7	Data I/O	54	N.C.	No connection
11	N.C.	No connection	55	N.C.	
12	N.C.			56	GND
13	A 0	Address input	57	A 1	Address input
14	A 2		58	A 3	
15	V <sub>cc</sub>	Power supply voltage	59	A 5	
16	A 4	Address input	60	A 7	
17	N.C.	No connection	61	A 9	
18	A 6	Address input	62	N.C.	No connection
19	A 8		63	GND	Ground
20	N.C.	No connection	64	N.C.	No connection
21	N.C.		65	RAS 1	Row address strobe 1
22	RAS 0	Row address strobe 0	66	CAS 2	Column address strobe 2
23	CAS 0	Column address strobe 0	67	GND	Ground
24	CAS 1	Column address strobe 1	68	CAS 3	Column address strobe 3
25	N.C.	No connection	69	RAS 3	Row address strobe 3
26	RAS 2	Row address strobe 2	70	WE	Write enable
27	V <sub>cc</sub>	Power supply voltage	71	PD 1 (N.C.)	Presence detect 1
28	PD 2 (GND)	Presence detect 2	72	PD 3 (GND)	Presence detect 3
29	PD 4 (GND)	Presence detect 4	73	GND	Ground
30	PD 6 (GND)	Presence detect 6	74	PD 5 (GND)	Presence detect 5
31	N.C.	No connection	75	PD 7 (N.C.)	Presence detect 7
32	N.C.		76	PD 8 (N.C.)	Presence detect 8
33	N.C.			77	N.C.
34	DQ 9	Data I/O	78	N.C.	
35	N.C.	No connection	79	N.C.	
36	DQ10	Data I/O	80	DQ27	Data I/O
37	V <sub>cc</sub>	Power supply voltage	81	DQ28	
38	DQ11	Data I/O	82	DQ29	
39	DQ12		83	DQ30	
40	DQ13		84	DQ31	
41	DQ14		85	DQ32	
42	DQ15		86	DQ33	
43	DQ16		87	DQ34	
44	GND	Ground	88	GND	Ground

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FUNCTION TABLE

Operation	Input					input/output		Refresh	Note
	RAS	CAS	WE	Row Address	Column Address	input	output		
Read	ACT	ACT	NAC	APD	APD	OPN	VLD	YES	Page mode identical
Early write	ACT	ACT	ACT	APD	APD	VLD	OPN	YES	
RAS-only refresh	ACT	NAC	DNC	APD	DNC	DNC	OPN	YES	
CAS before RAS refresh	ACT	ACT	NAC	DNC	DNC	DNC	OPN	YES	
Standby	NAC	DNC	DNC	DNC	DNC	DNC	OPN	NO	

Note 1 : ACT : active, NAC : nonactive, DNC : don't care, VLD : valid, APD : applied, OPN : open  
 Odd numbered RAS signals (RAS1, RAS3) and even numbered RAS signals (RAS0, RAS2) should not be active at the same time during Read and Early write cycles. This comment does not apply to MF12M1-L57ATXX series cards.

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Conditions	Rated	Unit
V <sub>CC</sub>	Supply voltage		-0.5~7	V
V <sub>I</sub>	Input voltage	With respect to GND	-0.5~V <sub>CC</sub> +0.5 (7 V MAX)	V
V <sub>O</sub>	Output voltage			-0.5~7
I <sub>O</sub>	Output current		50	mA
P <sub>d</sub>	Power dissipation	T <sub>a</sub> =25°C	No1	W
			4	
T <sub>opr</sub>	Operating temperature		0~55	°C
T <sub>stg</sub>	Storage temperature		-40~80	°C

RECOMMENDED OPERATING CONDITIONS (T<sub>a</sub>= 0~55°C, unless otherwise noted) : (Note 2)

Symbol	Parameter	Limits			Unit
		Min.	Typ.	Max.	
V <sub>CC</sub>	Supply voltage	4.75	5	5.25	V
GND	Supply voltage	0	0	0	V
V <sub>IH</sub>	High input voltage	0.7×V <sub>CC</sub>		V <sub>CC</sub>	V
V <sub>IL</sub>	Low input voltage	0		0.8	V

Note 2 : With respect to GND

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**ELECTRICAL CHARACTERISTICS** ( $T_a = 0 \sim 55^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$ ,  $\text{GND} = 0\text{V}$ ) : (Note 3)  
(MF12M1-L57ATXX)

Symbol	Parameter	Test condition	Limits				Unit	
			Min.		Typ.	Max.		
$V_{OH}$	High-level output voltage	$I_{OH} = -5\text{mA}$	2.4			$V_{CC}$		V
$V_{OL}$	Low-level output voltage	$I_{OL} = 4.2\text{mA}$	0			0.4		V
$I_{OZ}$	Off-state output current	$0\text{V} \leq V_{out} \leq V_{CC}$	No.1 -10	No.2 -20		No.1 10	No.2 20	$\mu\text{A}$
$I_I$	Input current	$0\text{V} \leq V_{in} \leq V_{CC}$ other input pins = 0V	-20			20		$\mu\text{A}$
$I_{CC1(AV)}$	Average supply current from $V_{CC}$ , operating (Note 4, 5)	RAS, CAS cycling $t_{RC} = t_{WC} = \text{min}$ , output open				No.1 460	No.2 480	mA
$I_{CC2(AV)}$	Supply current from $V_{CC}$ , Standby	$\overline{\text{RAS}} = \overline{\text{CAS}} \geq V_{CC} - 0.2\text{V}$ other input pins $\geq V_{CC} - 0.2\text{V}$ or $\leq 0.2\text{V}$ , output open				No.1 0.6	No.2 1	mA
$I_{CC3(AV)}$	Average supply current from $V_{CC}$ , refreshing (Note 4)	RAS cycling, $\overline{\text{CAS}} = V_{IH}$ $t_{RC} = \text{min}$ , output open				No.1 460	No.2 890	mA
$I_{CC4(AV)}$	Average supply current from $V_{CC}$ , Page-mode (Note 4, 5)	$\overline{\text{RAS}} = V_{IL}$ , CAS cycling $t_{RC} = \text{min}$ , output open				No.1 520	No.2 550	mA
$I_{CC6(AV)}$	Average supply current from $V_{CC}$ , CAS before RAS refresh mode (Note 4)	CAS before RAS refresh cycling $t_{RC} = \text{min}$ , output open				No.1 390	No.2 770	mA
$I_{CC8(AV)}$	Average supply current from $V_{CC}$ , Extended refresh mode (Note 6)	CAS before RAS refresh cycling $\overline{\text{WE}} \geq V_{CC} - 0.2\text{V}$ other input pins $\geq V_{CC} - 0.2\text{V}$ or $\leq 0.2\text{V}$ , output open $t_{RC} = 125\mu\text{s}$ , $t_{RAS}(\text{min}) \sim 1\mu\text{s}$				No.1 1.8	No.2 3	mA

Note 3 : Current flowing into a CARD is positive, out is negative.

4 :  $I_{CC1(AV)}$ ,  $I_{CC3(AV)}$ ,  $I_{CC4(AV)}$  and  $I_{CC6(AV)}$  are dependent on cycle rate.  
Specified values are obtained at the fastest cycle rate.

5 :  $I_{CC1(AV)}$  and  $I_{CC4(AV)}$  are dependent on output loading.  
Specified values are obtained with the outputs open.

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**SWITCHING CHARACTERISTICS** ( $T_a = 0 \sim 55^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$ ,  $\text{GND} = 0\text{V}$ ): (Note 6)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCAC	Access time from CAS (Note 7, 8)		27	ns
tRAC	Access time from RAS (Note 7, 9)		70	ns
tCAA	Column Address access time (Note 7, 10)		42	ns
tOFF	Output disable time after CAS high (Note 11)	0	27	ns

Note 6 : An initial pause of 500  $\mu\text{s}$  is required after power-up followed by any 8 RAS or RAS/CAS cycles before proper device operation is achieved.

Note that RAS may be cycled during the initial pause. And any 8 RAS or RAS/CAS cycles are required after prolonged periods of RAS inactivity before proper device operation is achieved.

7 : Measured with a load circuit equivalent to 2TTL Load and 100pF.

8 : Assumes that  $t_{RCD} \geq t_{RCD}(\text{max})$  and  $t_{ASC} \geq t_{ASC}(\text{max})$ .

9 : Assumes that  $t_{RCD} \leq t_{RCD}(\text{max})$  and  $t_{RAD} \leq t_{RAD}(\text{max})$ .

10 : Assumes that  $t_{RAD} \geq t_{RAD}(\text{max})$  and  $t_{ASC} \leq t_{ASC}(\text{max})$ .

11 : tOFF(max) define the time at which the output achieves the high impedance state(MF12M1-L57ATXX: |OUT|  $\leq 10\ \mu\text{A}$ , MF14M1-L57ATXX: |OUT|  $\leq 20\ \mu\text{A}$ ) and are not reference to  $V_{OH}(\text{min})$  or  $V_{OL}(\text{max})$ .

**TIMING REQUIREMENTS** ( $T_a = 0 \sim 55^\circ\text{C}$ ,  $V_{CC} = 5\text{V} \pm 5\%$ ,  $\text{GND} = 0\text{V}$ ): (Note 12, 13)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tREF	Refresh cycle time		128	ms
tRP	RAS high pulse width	50		ns
tRCD	Delay time, RAS low to CAS low (Note14)	20	43	ns
tCRP	Delay time, CAS high to RAS low (Note15)	17		ns
tRPC	Precharge to CAS active time.	0		ns
tCPN	CAS high pulse width	10		ns
tRAD	Column address delay time from RAS low (Note16)	17	28	ns
tASR	Row address setup time before RAS low	10		ns
tASC	Column address setup time before CAS low (Note17)	5	10	ns
tRAH	Row address hold time after RAS low	10		ns
tCAH	Column address hold time after CAS low	15		ns
tT	Transition time (Note18)	3	50	ns

Note 12 : The timing requirements are assumed  $t_T = 5\text{ ns}$ .

13 :  $V_{IH}(\text{min})$  and  $V_{IL}(\text{max})$  are reference levels for measuring timing of input signals.

14 :  $t_{RCD}(\text{max})$  is specified as a reference point only.

If  $t_{RCD} \geq t_{RCD}(\text{max})$ , access time is defined as tCAC and tCAA.

15 : tCRP requirement is applicable for all RAS/CAS cycles.

16 :  $t_{RAD}(\text{max})$  is specified as a reference point only.

If  $t_{RAD} \geq t_{RAD}(\text{max})$ ,  $t_{ASC} \leq t_{ASC}(\text{max})$ , access time is assumed by tCAA for read cycle.

17 : tASC(max) is specified as a reference point only of address access time.

18 : tT is measured between  $V_{IH}(\text{min})$  and  $V_{IL}(\text{max})$ .

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Read and Refresh Cycles

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tRC	Read cycle time	130		ns
tRAS	RAS low pulse width	70	10000	ns
tCAS	CAS low pulse width	20	10000	ns
tCSH	CAS hold time after RAS low	70		ns
tRSH	RAS hold time after CAS low	27		ns
tRCS	Read setup time before CAS low	5		ns
tRCH	Read hold time after CAS high	0		ns
tRRH	Read hold time after RAS high	10		ns

Write Cycle (Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tWC	Write cycle time	130		ns
tRAS	RAS low pulse width	70	10000	ns
tCAS	CAS low pulse width	20	10000	ns
tCSH	CAS hold time after RAS low	70		ns
tRSH	RAS hold time after CAS low	27		ns
twCS	Write setup time before CAS low	5		ns
twCH	Write hold time after CAS low	15		ns
tDS	Data setup time	10		ns
tDH	Data hold time after CAS low	22		ns

Page Mode Cycle (Read, Early Write)

Symbol	Parameter	Limits		Unit
		Min.	Max.	
tPC	Read, Write cycle time	55		ns
tCP	CAS high pulse width	10		ns
tRAS	RAS low pulse width ( Note 19)	125	10000	ns

Note 19 : tRAS(min) is specified the following formula as two cycles of CAS input are executed.  
 $tRAS(\min) = tCSH(\min) + tPC(\min)$ .

CAS before RAS Refresh Cycle (Note 20)

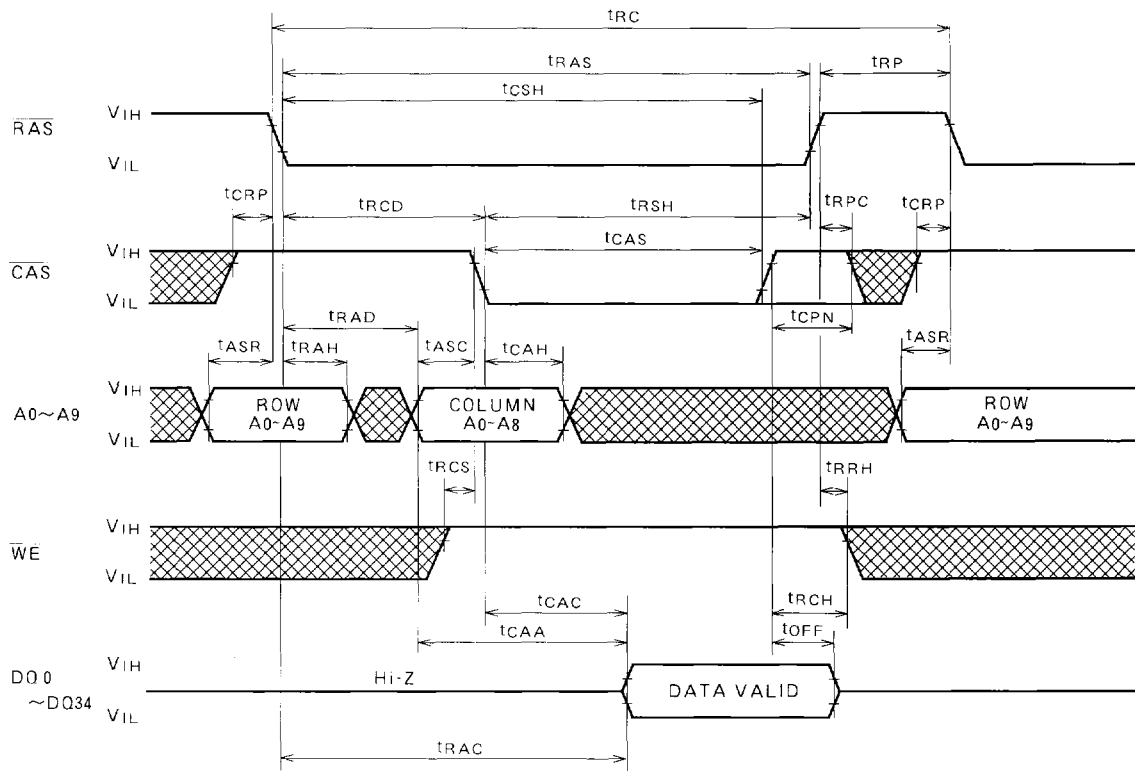
Symbol	Parameter	Limits		Unit
		Min.	Max.	
tCSR	CAS setup time for CAS before RAS refresh	20		ns
tCHR	CAS hold time for CAS before RAS refresh	15		ns

Note 20 : Eight or more CAS before RAS cycles are necessary for proper operation of CAS before RAS refresh mode.

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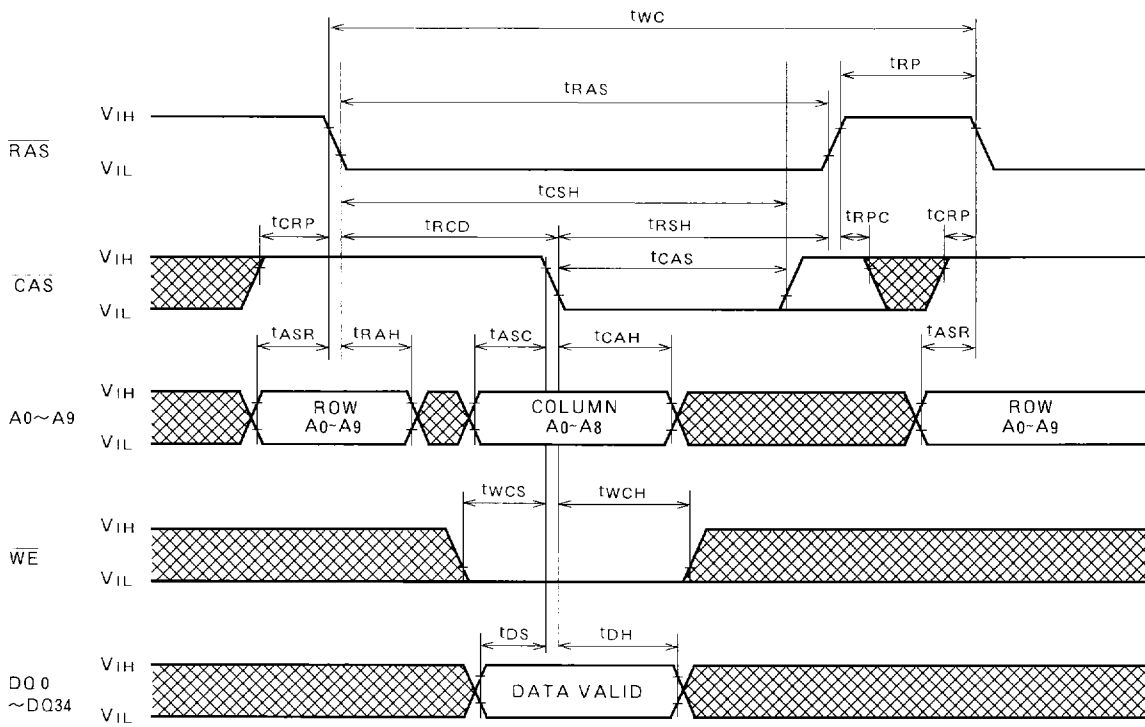
TIMING DIAGRAMS (Note 21)

Read Cycle



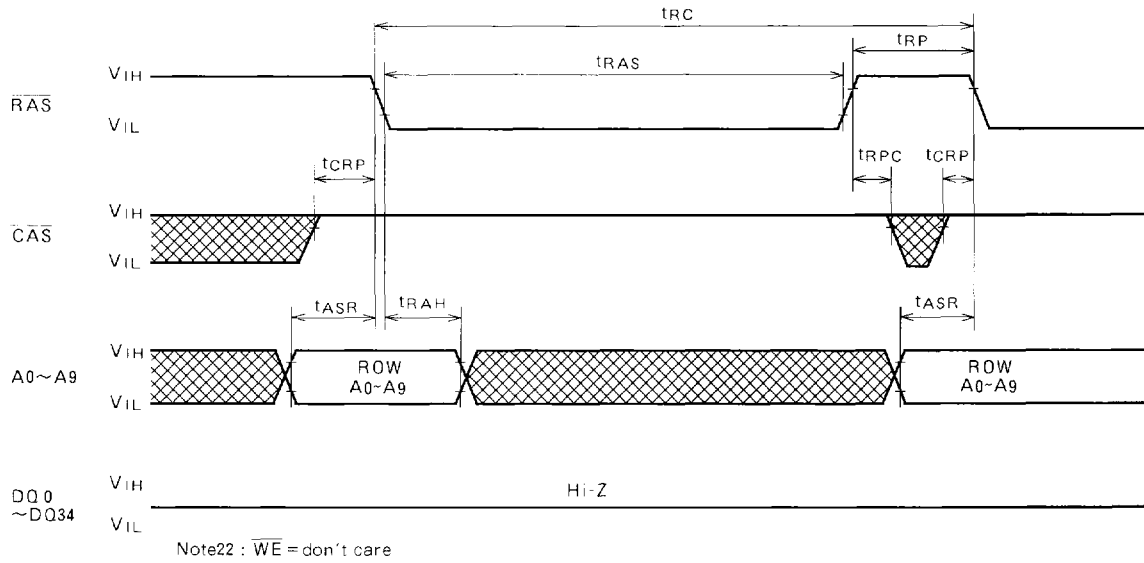
Note21 :  indicates the don't care input

Early Write Cycle

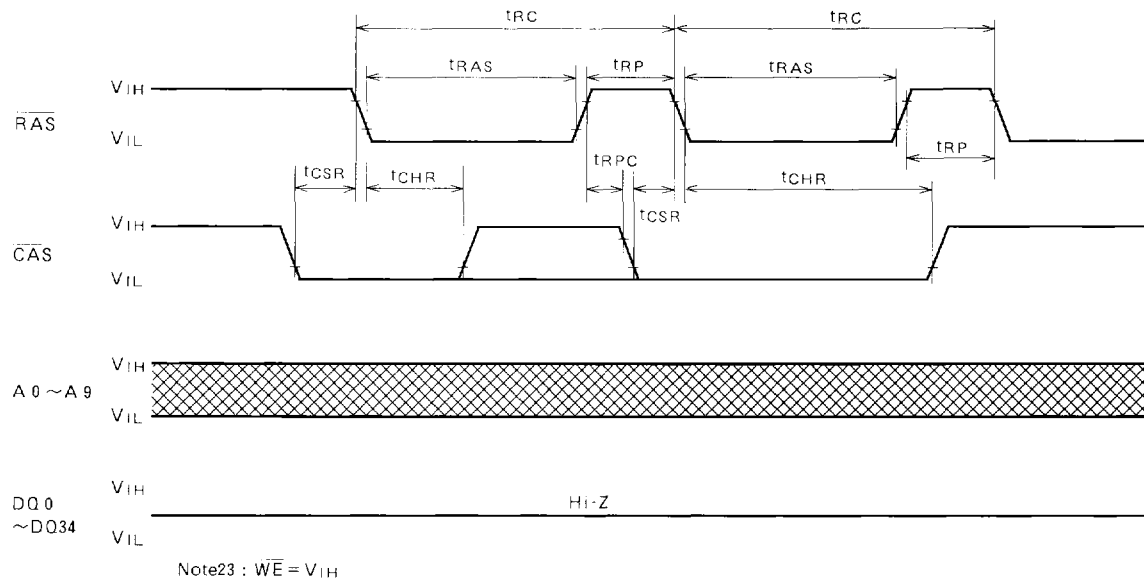


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**RAS only Refresh Cycle** (Note 22)

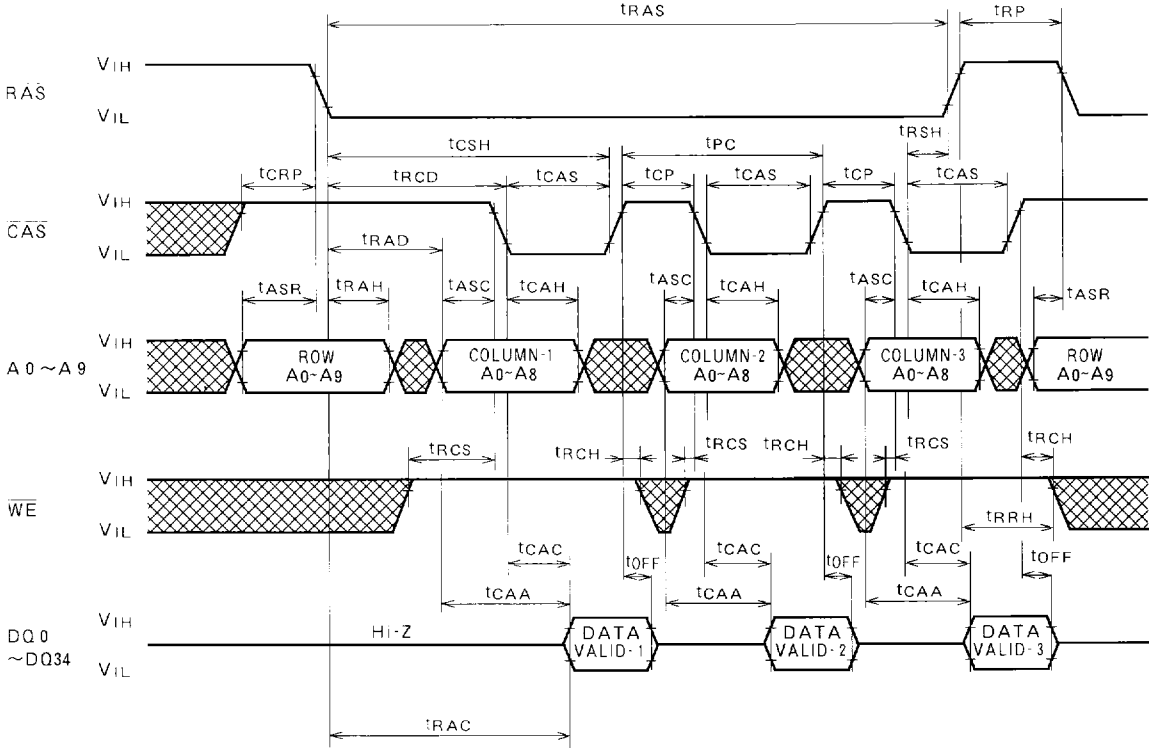


**CAS before RAS Refresh Cycle** (Note 23)



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Page-Mode Read Cycle



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Page-Mode Early Write Cycle

